

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3112100

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALAN B. BOTULA	06/17/2013
JEFFREY E. HANRAHAN	06/17/2013
MARK D. JAFFE	06/17/2013
ALVIN J. JOSEPH	06/26/2013
DALE W. MARTIN	06/17/2013
GERD PFEIFFER	06/17/2013
JAMES A. SLINKMAN	06/17/2013
RECEIVING PARTY DATA	
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	NEW ORCHARD ROAD
City:	ARMONK
State/Country:	NEW YORK
Postal Code:	10504
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14546058
CORRESPONDENCE DATA	
Fax Number:	(410)630-1656
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	410-705-6400
Email:	gunther@gibbiplaw.com
Correspondent Name:	FREDERICK W. GIBB, III GIBB & RILEY, LLC
Address Line 1:	844 WEST STREET
Address Line 2:	SUITE 100
Address Line 4:	ANNAPOLIS, MARYLAND 21401
ATTORNEY DOCKET NUMBER:	BUR920130089US2
NAME OF SUBMITTER:	JEFFREY C. MAYNARD
SIGNATURE:	/Jeffrey C. Maynard/
DATE SIGNED:	11/18/2014

PATENT

Total Attachments: 14

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DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT

Title of Invention: HIGH LINEARITY SOI WAFER FOR LOW-DISTORTION CIRCUIT APPLICATIONS

As a below named and undersigned inventor, I hereby declare that:

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Whereas, I ("ASSIGNOR") have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

Whereas, International Business Machines Corporation (herein referred to as the "ASSIGNEE"), a corporation of New York having a place of business at Armonk, New York, desires to acquire, and I desire to grant to the ASSIGNEE, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefore in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the ASSIGNEE, its successors, legal representatives, and assigns, whenever requested by the ASSIGNEE, its successors, legal representatives, or assigns.

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(1) Legal Name of Inventor: Alan B. Botula

Signature: Alan B. Botula Date: 6-17-2013

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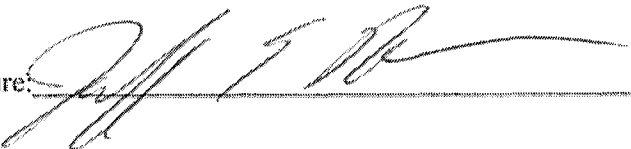
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(1) Legal Name of Inventor: Jeffrey E. Hanrahan

Signature:  Date: 6/17/2013

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(1) Legal Name of Inventor: Mark D. Jaffe

Signature: Mark D. Jaffe Date: 6/17/2013

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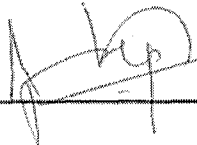
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(1) Legal Name of Inventor: **Alvin J. Joseph**

Signature:  _____ Date: 6/26/2013

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(1) Legal Name of Inventor: Dale W. Martin

Signature: Dale W Martin Date: 6/17/2013

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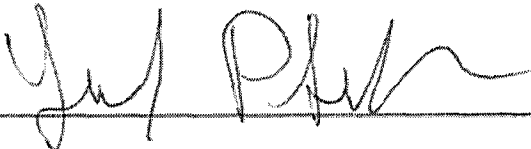
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Signature: James A. Slinkman Date: 6/17/2013